**Engineering Chip Packaging for Enhanced Performance in Superconducting Quantum Processors**

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The packaging of a quantum chip plays a critical role in its performance, influencing factors such as temperature stability, protection from external radiation, signal integrity, and overall efficiency. In this presentation, I will discuss findings from our recent experiments, where we evaluated various chip package designs to assess their impact on key parameters, including signal quality, thermal stability, and resilience to external interference. Additionally, we will explore packaging strategies that could enable the development of next-generation quantum chips with larger qubit arrays. This talk highlights the essential role of packaging in advancing quantum technology.